

Title (en)

METHOD FOR THE HEAT TREATMENT OF A PROFILE, DEVICE FOR THE HEAT TREATMENT OF A PROFILE AND PROFILE

Title (de)

VERFAHREN ZUR WÄRMEBEHANDLUNG EINES PROFILS, VORRICHTUNG ZUR WÄRMEBEHANDLUNG EINES PROFILS SOWIE PROFIL

Title (fr)

PROCÉDÉ DE TRAITEMENT THERMIQUE D'UN PROFILÉ, DISPOSITIF DE TRAITEMENT THERMIQUE D'UN PROFILÉ ET PROFILÉ

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Application

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Abstract (en)

[origin: WO2007118489A1] The invention relates firstly to a method for the heat treatment of a profile (1, 26), in particular an extruded profile for aircraft. Furthermore, the invention relates to a device for the heat treatment of such a profile (1, 26). In addition, the invention relates to such a profile (1, 26), heat-treated by the method according to the invention. The profile (1, 26) may in this case be formed by one or more different, in particular curable, aluminium alloys. The method according to the invention provides that at least two regions (2, 3, 37, 38) of a profile (1, 26) are subjected to a different heat treatment. The device for carrying out the method according to the invention is characterized in that a first chamber (17) encloses a first region (2, 37) of a profile (1, 26) and a second chamber (18) encloses a second region (3, 38) of the profile (1, 26), wherein different temperatures can be set in the first and second chambers (17, 18). The profile (1, 26) produced by the method according to the invention and with the device according to the invention has at least two regions (2, 3, 37, 38) that each have different material properties and are formed by differential heat treatment.

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